

Complementary PowerTrench MOSFET

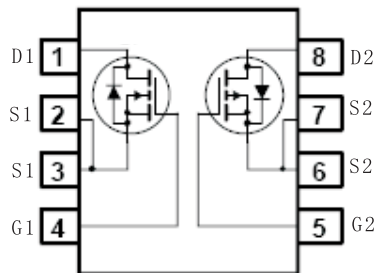
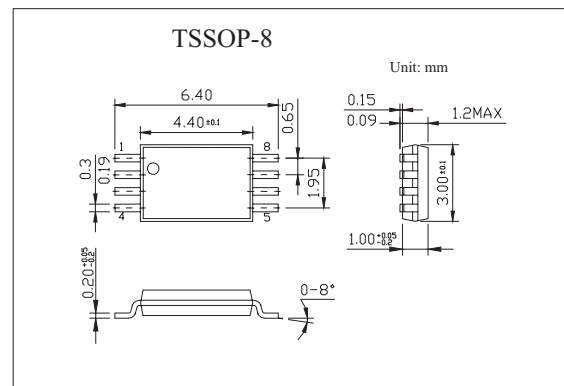
KDW2521C

■ Features

● N-Channel

5.5 A, 20 V $R_{DS(ON)} = 21\text{ m}\Omega$ @ $V_{GS} = 4.5\text{ V}$ $R_{DS(ON)} = 35\text{ m}\Omega$ @ $V_{GS} = 2.5\text{ V}$

● P-Channel

-3.8 A, 20 V $R_{DS(ON)} = 43\text{ m}\Omega$ @ $V_{GS} = -4.5\text{ V}$ $R_{DS(ON)} = 70\text{ m}\Omega$ @ $V_{GS} = -2.5\text{ V}$ ● High performance trench technology for extremely low $R_{DS(ON)}$ ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	N-Channel	P- Channel	Unit
Drain to Source Voltage	V_{DS}	20	-20	V
Gate to Source Voltage	V_{GS}	± 12	± 12	V
Drain Current Continuous (Note 1a)	I_D	5.5	-3.8	A
Drain Current Pulsed		30	-30	A
Power Dissipation for Single Operation (Note 1a) (Note 1b)	P_D	1		W
		0.6		
Operating and Storage Temperature	T_J, T_{STG}	-55 to 150		$^\circ\text{C}$
Thermal Resistance Junction to Ambient (Note 1a) (Note 1b)	$R_{\theta JA}$	125		$^\circ\text{C}/\text{W}$
		208		$^\circ\text{C}/\text{W}$

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■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditions	Min	Typ	Max	Unit	
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0 V, I _D = 250 μA	N-Ch	20		V	
		V _{GS} = 0 V, I _D = -250 μA	P-Ch	-20			
Breakdown Voltage Temperature Coefficient	$\frac{\Delta BV_{DSS}}{\Delta T_J}$	I _D = 250 μA, Referenced to 25°C	N-Ch		14	mV/°C	
		I _D = -250 μA, Referenced to 25°C	P-Ch		-16		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 16V, V _{GS} = 0 V	N-Ch		1	μA	
		V _{DS} = -16 V, V _{GS} = 0 V	P-Ch		-1		
Gate-Body Leakage	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0 V	N-Ch		±100	nA	
		V _{GS} = ±12 V, V _{DS} = 0 V	P-Ch		±100		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	N-Ch	0.6	0.8	1.5	V
		V _{DS} = V _{GS} , I _D = -250 μA	P-Ch	-0.6	-1.0	-1.5	
Gate Threshold Voltage Temperature Coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	I _D = 250 μA, Referenced to 25°C	N-Ch		-3.2	mV/°C	
		I _D = -250 μA, Referenced to 25°C	P-Ch		3.0		
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 5.5A	N-Ch		17	21	mΩ
		V _{GS} = 2.5 V, I _D = 4.2 A			24	35	
		V _{GS} = 4.5 V, I _D = 5.5 A, T _J = 125°C			23	34	
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = -4.5 V, I _D = -3.8 A	P-Ch		36	43	
		V _{GS} = -2.5 V, I _D = -3.0 A			56	70	
		V _{GS} = -4.5 V, I _D = -3.8A, T _J = 125°C			49	69	
On-State Drain Current	I _{D(on)}	V _{GS} = 4.5 V, V _{DS} = 5V	N-Ch	30		A	
		V _{GS} = -4.5 V, V _{DS} = -5V	P-Ch	-15			
Forward Transconductance	g _{FS}	V _{DS} = 5V, I _D = 5.5A	N-Ch		26	S	
		V _{DS} = -5V, I _D = -3.5A	P-Ch		13.2		
Input Capacitance	C _{iss}	N-Channel V _{DS} = 10 V, V _{GS} = 0 V, f = 1.0 MHz	N-Ch		1082	pF	
			P-Ch		1030		
Output Capacitance	C _{oss}	P-Channel V _{DS} = -10 V, V _{GS} = 0 V, f = 1.0 MHz	N-Ch		277	pF	
			P-Ch		280		
Reverse Transfer Capacitance	C _{rss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1.0 MHz	N-Ch		130	pF	
			P-Ch		120		
Turn-On Delay Time	t _{d(on)}	N-Channel V _{DD} = 10 V, I _D = 1 A,	N-Ch	8	20	ns	
			P-Ch	11	20		
Turn-On Rise Time	t _r	V _{GS} = 4.5 V, R _{GEN} = 6 Ω (Note 2)	N-Ch	8	27	ns	
			P-Ch	18	32		
Turn-Off Delay Time	t _{d(off)}	P-Channel V _{DD} = -10 V, I _D = -1 A,	N-Ch	24	38	ns	
			P-Ch	34	55		
Turn-Off Fall Time	t _f	V _{GS} = -4.5 V, R _{GEN} = 6 Ω (Note 2)	N-Ch	8	16	ns	
			P-Ch	34	55		
Total Gate Charge	Q _g	N-Channel V _{DS} = 10V, I _D = 5.5A, V _{GS} = 4.5V	N-Ch	12	17	nC	
			P-Ch	9.7	16		
Gate-Source Charge	Q _{gs}	(Note 2) P-Channel	N-Ch	2		nC	
			P-Ch	2.2			
Gate-Drain Charge	Q _{gd}	V _{DS} = -5V, I _D = -3.8A, V _{GS} = -4.5V (Note 2)	N-Ch	3		nC	
			P-Ch	2.4			

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Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Maximum Continuous Drain-Source Diode Forward Current	Is	N-Ch			0.83	A
		P-Ch			-0.83	
Drain-Source Diode Forward Voltage	VSD	VGS = 0 V, Is = 0.83A (Not 2)	N-Ch	0.7	1.2	V
		VGS = 0 V, Is = -0.83A (Not 2)	P-Ch	-0.7	-1.2	

Notes:

- R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design while R_{θCA} is determined by the user's board design.
 - R_{θJA} is 125°C/W (steady state) when mounted on a 1 inch² copper pad on FR-4.
 - R_{θJA} is 208°C/W (steady state) when mounted on a minimum copper pad on FR-4.
- Pulse Test: Pulse Width < 300 μs, Duty Cycle < 2.0%